### **Multilayer Ceramic Chip Capacitors**

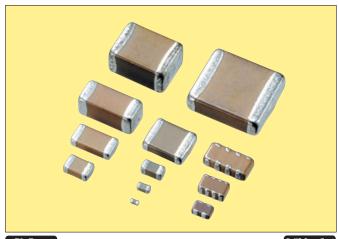


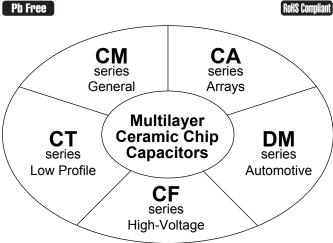


Kyocera's series of Multilayer Ceramic Chip Capacitors are designed to meet a wide variety of needs. We offer a complete range of products for both general and specialized applications, including the general-purpose CM series, the high-voltage CF series, the low profile CT series, and the DM series for automotive uses.

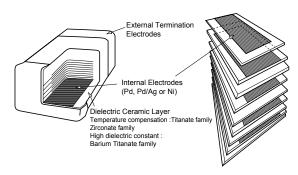
#### **Features**

- We have factories worldwide in order to supply our global customer bases quickly and efficiently and to maintain our reputation as one of the highest-volume producers in the industry.
- All our products are highly reliable due to their monolithic structure of high-purity and superfine uniform ceramics and their integral internal electrodes.
- By combining superior manufacturing technology and materials with high dielectric constants, we produce extremely compact components with exceptional specifications.
- Our stringent quality control in every phase of production from material procurement to shipping ensures consistent manufacturing and super quality.
- Kyocera components are available in a wide choice of dimensions, temperature characteristics, rated voltages, and terminations to meet specific configurational requirements.

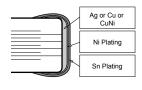




#### **Structure**



Nickel Barrier Termination Products



### **Tape and Reel**

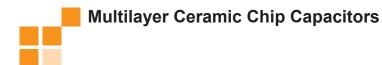


**Bulk Cassette** 



Please contact your local AVX, Kyocera sales office or distributor for specifications not covered in this catalog.

Our products are continually being improved. As a result, the capacitance range of each series is subject to change without notice. Please contact an sales representative to confirm compatibility with your application.





Kyocera Ceramic Chip Capacitors are available for different applications as classified below:

Series	Dieletric Options	Typical Applications	Features	Terminations	Available Size
СМ	C0G (NP0) X5R X7R *X6S *X7S Y5V	General Purpose	Wide Cap Range	Nickel Barrier	0201, 0402, 0603 0805, 1206, 1210 1812
CF	C0G (NP0) X7R	High Voltage & Power Circuits	High Voltage 250VDC, 630VDC 1000VDC, 2000VDC 3000VDC, 4000VDC	Nickel Barrier	0805, 1206, 1210 1812, 2208, 1808 2220
СТ	C0G (NP0) X5R X7R Y5V	PLCC (Decoupling)	Low Profile	Nickel Barrier	0402, 0603, 0805 1206, 1210
DM	X7R	Automotive	Thermal shock Resistivity High Reliability	Nickel Barrier	0603, 0805, 1206
CA	C0G (NP0) X5R, X7R	Digital Signal Pass line	Reduction in Placing Costs	Nickel Barrier	0405, 0508

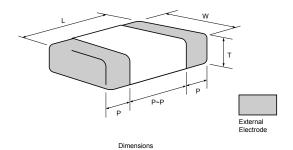
\* option

# **Multilayer Ceramic Chip Capacitors**





# **Dimensions**



### Tape & Reel

1 ape o	· ixeei							
Size	EIA CODE	EIAJ CODE			Dimensi	ons (mm)		
Oize	LIA GODE	LIAU GODE	L	w	P min.	P max.	P to P min.	T max.
03	0201	0603	0.6±0.03	0.3±0.03	0.13	0.23	0.20	0.33
05	0402	1005	1.0±0.05	0.5±0.05	0.15	0.35	0.30	0.55
105	0603	1608	1.6±0.10	0.8±0.10	0.20	0.60	0.50	0.90
21	0805	2012	2.0±0.10	1.25±0.10	0.20	0.75	0.70	1.35
316	1206	3216	3.2±0.20	1.60±0.15	0.30	0.85	1.40	1.75
32	1210	3225	3.2±0.20	2.50±0.20	0.30	1.00	1.40	2.70
42	1808	4520	4.5±0.20	2.00±0.20	0.15	0.85	2.60	2.20
43	1812	4532	4.5±0.30	3.20±0.20	0.30	1.10	2.00	3.0
52	2208	5720	5.7±0.40	2.00±0.20	0.15	0.85	4.20	2.20
53	2211	5728	5.7±0.40	2.80±0.20	0.15	0.85	4.20	2.80
55	2220	5750	5.7±0.40	5.00±0.40	0.30	1.40	2.50	2.70

### **Bulk Cassette**

Size	EIA CODE	EIAJ CODE	-	w	_	F	•	P to P				
Size	EIA CODE	LIAU OODL	_	VV	·	min.	max.	min.				
05	0402	1005	1.0±0.05	0.5±0.05	0.5±0.05	0.15	0.35	0.30				
105	0603	1608	1.6±0.07	0.8±0.07	0.8±0.07	0.20	0.60	0.50				
21	0805	2012	2.0±0.1	1.25±0.1	1.25±0.1	0.20	0.75	0.70				

Note) Regarding support for Bulk cases, please contact us for further information.

<sup>T (Thickness) depends on capacitance value.
Standard thickness is shown on the appropriate product pages.
CA series (please refer applicable page)</sup> 



#### 104 **KYOCERA PART NUMBER:** CM 21 X7R Κ 50 SERIES CODE -CM General Purpose CA = Capacitor Arrays CF High Voltage = CT Low Profile Automotive DM SIZE CODE — SIZE EIA (EIAJ) SIZE EIA (EIAJ) SIZE EIA (EIAJ) 21 = 0805 (2012)03 = 0201 (0603)52 = 2208 (5720) 05 = 0402 (1005)316 = 1206 (3216)53 = 2218 (5732) 105 = 0603 (1608)32 = 1210 (3225)55 = 2220 (5750)42 D11 = 0405 (1012)/2capF12 = 0508 (1220)/4cap = 1808 (4520) 43 = 1812 (4532) D12 = 0508 (1220)/2cap**DIELECTRIC CODE** CODE EIA CODE CG = C0G (NPO)X7S = X7S (Option)X6S = X6S (Option) X5R = X5RX7R = X7RY5V = Y5VNegative dielectric types are available on request. **CAPACITANCE CODE** Capacitance expressed in pF. 2 significant digits plus number of zeros. For Values < 10pF, Letter R denotes decimal point, eg. 100000pF = 1041.5pF = 1R5 0.1μF = 104 0.5pF = R504700pF = 472 100μF 107 **TOLERANCE CODE** Z = -20 to +80% $A = \pm 0.05pF$ (option) $D = \pm 0.5pF$ $J~=~\pm 5\%$ $B = \pm 0.1pF$ (option) $F = \pm 1pF$ $K = \pm 10\%$ $C=\pm 0.25 pF$ $G = \pm 2\%$ $M = \pm 20\%$ **VOLTAGE CODE** = 4VDC = 100VDC 04 100 1000 = 1000VDC06 = 6.3VDC 250 = 250VDC 2000 = 2000VDC 10 = 10VDC 400 400VDC 3000 = 3000VDC 16 = 16VDC 630 = 630VDC 4000 = 4000VDC25 = 25VDC 35 = 35VDC = 50VDC **TERMINATION CODE** A = Nickel Barrier **PACKAGING CODE** L = 13" Reel Taping & 4mm Cavity pitch H = 7" Reel Taping & 2mm Cavity pitch C = Bulk Cassette (option)

N = 13" Reel Taping & 2mm Cavity pitch

#### **OPTION**

Thickness max value is indicated in CT series

T = 7" Reel Taping & 4mm Cavity pitch

EX. 125  $\rightarrow$  1.25mm max. 095  $\rightarrow$  0.95mm max.



### **High Dielectric Constant**

EIA Dielectric	Temperature Range	∆Cmax
X5R	–55 to 85°C	±15%
X7R	–55 to 125°C	±1370
X7S	–55 to 125°C	+22%
X6S	–55 to 105°C	±22%
Y5V	-30 to 85°C	-82 to +22%

### **Temperature Compensation Type**

Electric Code Value (pF)	COG	U∆ N750	SL +350 to -1000
0.5-2.7	CK	UK	SL
3.0-3.9	CJ	UJ	SL
4.0-9.0	СН	UJ	SL
≥10	CG	UJ	SL

 $K=\pm 250 ppm/^{\circ}C,\ J=\pm 120 ppm/^{\circ}C,\ H=\pm 60 ppm/^{\circ}C,\ G=\pm 30 ppm/^{\circ}C$ 

Note: All parts will be marked as "CG" but will conform to the above table.

### **Available Tolerances**

Dielectric materials, capacitance values and tolerances are available in the following combinations only:

EIA Dielectric	Tolerance	Capacitance
	C=±0.25pF	
	D=±0.50pF	*1 <10pF
	F=±1pF	
cog	*3 A=±0.05pF	<0.5pF
300	B=±0.1pF	≤5pF
	G=±2%	>40~F
	J=±5%	≥10pF
	K=±10%	E12 Series
X5R	*2 K=±10%	FC Corios
X6R X7R	M=±20%	E6 Series
Y5V	Z=-20% to +80%	E3 Series

#### Note:

### **E Standard Number**

E3	E6	E12	E24 (C	Option)
	1.0	1.0	1.0	1.1
1.0	1.0	1.2	1.2	1.3
1.0	1.5	1.5	1.5	1.6
	1.5	1.8	1.8	2.0
	2.2	2.2	2.2	2.4
2.2	2.2	2.7	2.7	3.0
2.2	3.3	3.3	3.3	3.6
	3.3	3.9	3.9	4.3
	4.7	4.7	4.7	5.1
4.7	4.7	5.6	5.6	6.2
4.7	6.8	6.8	6.8	7.5
	0.0	8.2	8.2	9.1

e.g. CG = 0±30ppm/°C

<sup>\*1</sup> Nominal values below 10pF are available in the standard values of 0.5pF, 1.0pF, 1.5pF, 2.0pF, 3.0pF, 4.0pF, 5.0pF, 6.0pF, 7.0pF, 8.0pF, 9.0pF

<sup>\*2</sup> J =  $\pm$ 5% for X7R(X5R) is available on request.

<sup>\*3</sup> option





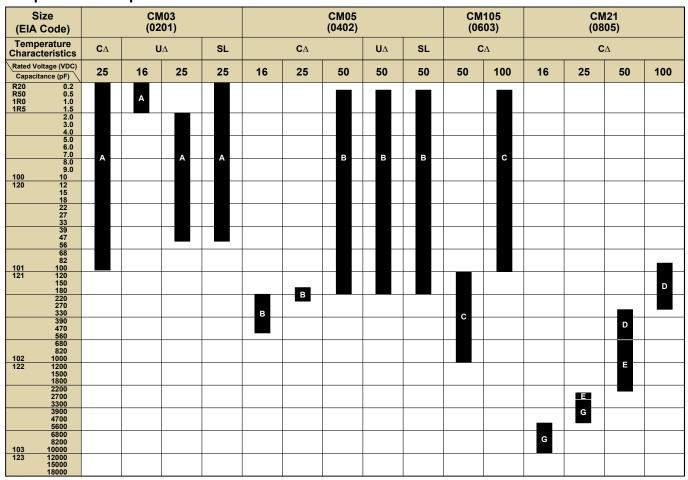
#### **Features**

We offer a diverse product line ranging from ultra-compact (0.6×0.3 mm) to large (5.7×5.0 mm) components configured for a variety of temperature characteristics, rated voltages, and packages. We offer the choice and flexibility for almost any applications.

### **Applications**

This standard type is ideal for use in a wide range of applications, from commercial to industrial equipment.

### **Temperature Compensation Dielectric**



### Thickness and standard package quantity

Size	*03	*05	105	*105					21, 316, 32				
Thickness	Α	В	С	С	D	Ε	F	G	Н		L	K	
(mm)	0.3±0.03	0.5±0.05	0.8±0.1	0.8±0.1	0.6±0.1	0.85±0.1	1.15±0.1	1.25±0.1	1.4max.	1.6max.	1.6±0.15	2.0±0.2	2.5±0.2
Taping (180 dia reel)	15kp(P8)	10kp(P8)	4kp(P8)	8kp(P8)	4kp(P8)	4kp(P8)	3kp(E8)	3kp(E8)	3kp(E8)	2.5kp(E8)	2.5kp(E8)	2kp(E8)	1kp(E8)
Taping (330 dia reel)	50kp(P8)	50kp(P8)	10kp(P8)	20kp(P8)	10kp(P8)	10kp(P8)	10kp(E8)	10kp(E8)	10kp(E8)	5kp(E8)	5kp(E8)	5kp(E8)	

Size		4	13	
Thickness	J	K		M
(mm)	1.6±0.15	2.0±0.2	2.5±0.2	2.8±0.2
Taping (180 dia reel)	1kp(E12)	1kp(E12)	0.5kp(E12)	0.5kp(E12)
Taping (330 dia reel)				

Note: P8 = 8mm width paper tape E8 = 8mm width plastic tape E12 = 12mm width plastic tape

<sup>\*</sup> Carrier tape 2mm pitch from one capacitor to another.



### **X5R Dielectric**

(EIA	Size CM03 (0201)						CM05 (0402)						CM (06	105 03)					CN (08	121 05)				
	Voltage (VDC)	4	6.3	10	16	25	4	6.3	10	16	25	50	4	6.3	10	16	25	50	4	6.3	10	16	25	50
101	100																							
151	150 220 330					A																		
102 152	470 680 1000											В												
152	1500 2200 3300				Α																			
103	4700 6800 10000			Α							В							С						
153	15000 22000 33000																							面回
104	47000 68000 100000									В							С	C						G
154	150000 220000 330000							В	В														G	
105	470000 680000 1000000						122A 177A	12/2 17/2	<u> </u>						С	С	P773					G		<i>1773</i>
155	1500000 2200000 3300000													<b>2</b> 22	<b>2</b> 222						G	G		
106	4700000 6800000 10000000												1221 12721							G	G	122A 127A		
156	15000000 22000000												V//A						7//	7/2		2,7,8		

Size (EIA Code)			CM316 (1206)						//32 (10)			CM43 (1812)		
Rated Voltage (VDC) Capacitance (pF)	6.3	10	16	25	50	4	6.3	10	16	25	50	6.3	50	
104 100000														
220000 470000 105 1000000				F	F						H K			
2200000 4700000 106 10000000	J	J	J	J				К		K L			L	
22000000 47000000 107 100000000							L	L				М		

Optional Spec.





# X7R, Dielectric

(EIA	Size A Code)	CN (02	103 (01)		CM05 (0402)				CM (06	105 03)				CN (08	CM21 (0805)			
Capa	Voltage (VDC)	10	16	16	25	50	6.3	10	16	25	50	100	6.3	10	16	25	50	100
101 151	100 150 220 330		A															
102 152	470 680 1000 1500					В						С						
132	2200 3300 4700	Α –			В													D
103 153	6800 10000			В							С							D E
153	15000 22000 33000									С							D E	G
104 154	47000 68000 100000								С	С	C						G	
154	150000 220000 330000							С							G	G		
105 155	470000 680000 1000000								7//2					G		7//2		
155	1500000 2200000 3300000																	
106	4700000 10000000												777					

	Size A Code)		CM316 (1206)						CM32 (1210)					143 12)
	Voltage (VDC)	6.3	10	16	25	50	100	10	16	25	50	100	50	100
103	10000													
	22000													
404	47000						F							
104	100000					Ę	J					H		
	220000 470000				<b></b>	F						K L		
105	1000000			F	F J					H	K	<b></b>	K	L
	2200000		J							K			L	
	4700000								L				_	
106	10000000							L						
	22000000	<i>V//</i> /							7///					

### **Y5V Dielectric**

	Size A Code)		103 01)			105 02)				105 03)			CN (08	121 05)			CM316 (1206)			CM32 (1210)	
	Voltage (VDC) citance (pF)	6.3	10	10	16	25	50	10	16	25	50	10	16	25	50	10	16	25	10	16	25
102 472	1000 2200 4700		A																		
103	10000 22000 47000	Α			В	В	В				С										
104	100000 220000 470000			В					С	С			E	D E	E G						
105	1000000 2200000 4700000							С				G	G	G			F	E			
106 476	10000000 22000000 47000000											Ŭ				J	J		K	1	ı

### Thickness and standard package quantity

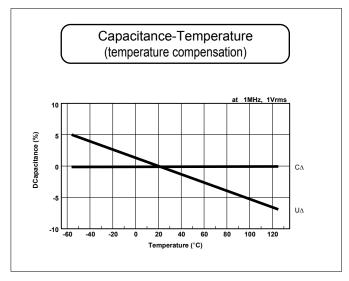
Size	*03	*05	105	*105		21, 316, 32							
Thickness	Α	В	С	С	D	E	F	G	H		J	K	
(mm)	0.3±0.03	0.5±0.05	0.8±0.1	0.8±0.1	0.6±0.1	0.85±0.1	1.15±0.1	1.25±0.1	1.4max.	1.6max.	1.6±0.15	2.0±0.2	2.5±0.2
Taping (180 dia reel)	15kp(P8)	10kp(P8)	4kp(P8)	8kp(P8)	4kp(P8)	4kp(P8)	3kp(E8)	3kp(E8)	3kp(E8)	2.5kp(E8)	2.5kp(E8)	2kp(E8)	1kp(E8)
Taping (330 dia reel)	50kp(P8)	50kp(P8)	10kp(P8)	20kp(P8)	10kp(P8)	10kp(P8)	10kp(E8)	10kp(E8)	10kp(E8)	5kp(E8)	5kp(E8)	5kp(E8)	

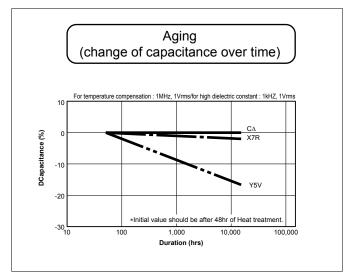
Size		43						
Thickness	J	K	L	M				
(mm)	1.6±0.15	2.0±0.2	2.5±0.2	2.8±0.2				
Taping (180 dia reel)	1kp(E12)	1kp(E12)	0.5kp(E12)	0.5kp(E12)				
Taping (330 dia reel)								

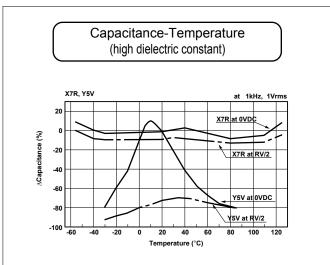
$$\label{eq:parameters} \begin{split} Note: & P8 = 8 mm \text{ width paper tape} \\ & E8 = 8 mm \text{ width plastic tape} \\ & E12 = 12 mm \text{ width plastic tape} \end{split}$$

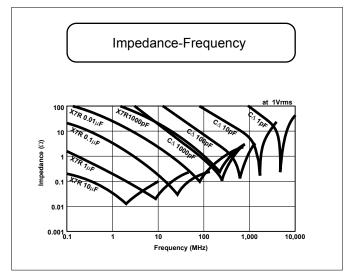
<sup>\*</sup> Carrier tape 2mm pitch from one capacitor to another.

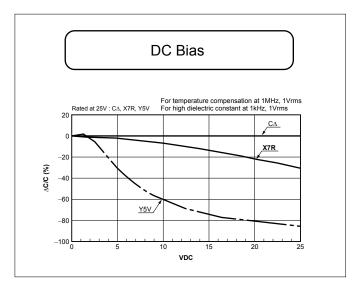


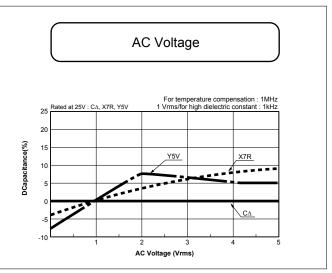




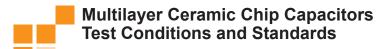








Please verify individual characteristics at the design stage to ensure total suitability





# Test Conditions and Specification for Temperature Compensation type (C∆ to U∆ • SL Characteristics)

Tes	t Items	Specification (C: nominal capacitance)	Test Conditions				
Capacitance	Value	Within tolerance	C≤1000pF 1MHz±10% 0.5 to				
Q		C≥30pF: Q≥1000 C<30pF: Q≥400+20C	C>1000pF 1kHz±10% 5Vrms				
Insulation re	esistance (IR) (*5)	10,000M $\Omega$ or 500M $\Omega$ •μF min., whichever is less	Measured after the rated voltage is applied for one minute at normal room temperature and humidity. (*3)				
Dielectric Re	esistance (*5)	No problem observed	(*1) Apply 3 times of the rated voltage for 1 to 5 seconds.				
Appearance		No problem observed	Microscope (10×magnification)				
Termination	strength	No problem observed	Apply a sideward force of 500g(5N) (*2) to a PCB-mounte sample.				
Bending strength		No mechanical damage at 1mm bent	Glass epoxy PCB (t=1.6mm); fulcrum Spacing: 90mm; for 10 seconds.				
Vibration Appearance		No significant change is detected	Vibration frequency: 10 to 55(Hz)				
1001	ΔC	Within tolerance	Amplitude: 1.5mm Sweeping condition: 10→55→10Hz/min				
	Q	C≥30pF: Q≥1000 C<30pF: Q≥400+20C	In X, Y and Z directions: 2 hours each Total 6 hours				
Soldering heat resistance $\Delta C$		No significant change is detected	Soak the sample in 260°C±5°C				
		±2.5% or ±0.25pF max., whichever is larger	solder for 10±0.5seconds and place in a room at normal temperatu				
		C≥30pF: Q≥1000 C<30pF: Q≥400+20C	and humidity; measure after 24±2hours. (Preheating Conditions)				
	<b>IR</b> (*5)	10,000MΩ or 500MΩ•μF min., whichever is smaller	1 80 to 100°C 2minutes				
Withstand voltage		Resists without problem	2 150 to 200°C 2minutes				
Solderability	,	Ni/Br termination: 90% min.	Sn63 Solder         235±5°C         2±0.5sec.           Sn-3Ag-0.5Cu         245±5°C         3±0.5sec.				
Temperature cycle	Appearance	No significant change is detected	(Cycle)  Normal room temperature (3min.)→  Lowest operation temperature (30min.)→  Normal room temperature (3min.)→  Highest operation temperature (30min.)→				
Cycle	ΔC	±2.5% or ±0.25pF max., whichever is larger					
	Q	C≥30pF: Q≥1000 C<30pF: Q≥400+20C					
	<b>IR</b> (*5)	10,000M $\Omega$ or 500M $\Omega^{\bullet}\mu F$ min., whichever is samller	After five cycles, measure after				
	Withstand voltage (*5)	Resists without problem	24±2hours.				
Load humidity	Appearance	No significant change is detected	After appling rated voltage for				
test (*4)	ΔC	$\pm 7.5\%$ or $\pm 0.75 pF$ max., whichever is larger	500+24/–0 hours in pre condition at 40±2°C, humidity 90 to 95%RH allow parts				
	Q	C≥30pF: Q≥200 C<30pF: Q≥100+10C/3	to stabilize for 48±4 hours, at room temperature before making measurements.				
	<b>IR</b> (*5)	$500 M\Omega$ or $25 M\Omega^{\bullet}\mu F$ min., whichever is smaller					
High- temperature	Appearance	No significant change is detected	After applying (*1) twice of the rated voltage				
with loading	ΔC	$\pm 3\%$ or $\pm 0.3$ pF max., whichever is larger	at a temperature of 125±3°C for 1000+48/–0hours, measure the sample				
Ū	Q	C≥30pF: Q≥350 10pF≤C<30pF: Q≥275+5C/2 C<10pF: Q≥200+10C	after storing 24±2hours.				
	<b>IR</b> (*5)	1,000MΩ or 50MΩ•μF min., whichever is smaller					
	. 450 1	on the rated voltage is 250V: use/1.2 times when \$4. Except CE					

<sup>\*1</sup> For the CF series, use 1.5 times when the rated voltage is 250V; use/1.2 times when the rated voltage exceeds 630V.

<sup>\*2 2</sup>N at 0201 Size

<sup>\*3</sup> Apply 500V for 1minite in case the rated voltage is 1000V or higher.

<sup>\*4</sup> Except CF series.

<sup>\*5</sup> The charge and discharge current of the capacitor must not exceed 50mA.



### Test Conditions and Specification for High Dielectric Type (X5R, X7R, Y5V)

Test Items		Specific		Te	st Condition			
		X7R/X5R	Y5V	Do previous treat				
Capacitance	e Value	Within tolerance		Capacitance	Fire	Vol		
tanδ (%)		2.5%max., 3.5%max. (*2), 7.0%max. (*12) 5.0%max. (*3), 7.5%max. (*17)	5.0%max., 7.0%max. (*13) 9.0%max. (*4), 12.5%max. (*5)	C≤10μF		1.0±0.1Vrms 0.5±0.1Vrms		
Insulation re	esistance (IR) (*15)	10,000MΩ or 500MΩ•μF min., w	hichever is less	Measured after the rated voltage is applied for 2minutes at normal room temperature and humidity. (*10)				
Dielectric R	esistance (*15)	No problem observed	(*1) Apply 2.5 times of the rated voltage for 1 to 5 seconds.					
Appearance		No problem observed		Microscope (10×	Microscope (10×magnification)			
Termination	strength (*6)	No problem observed	Apply a sideward force PCB-mounted sample		6) to a			
Bending str	ength test (*6)	No problem observed at 1mm be	Glass epoxy PCB (*03,0 Spacing: 90mm; for 10		es: T=0.8mm); fulcrum			
Vibration Appearance		No significant change is detecte	d	Vibration frequer		Hz)		
test ΔC tanδ (%)  Soldering Appearance		Within tolerance		Amplitude: 1.5m Sweeping condit	ion: 10→55–	10Hz/min		
		Satisfies the initial value	In X, Y and Z directly 2 hours each To					
		No significant change is detecte	Do previous treatment (*8) Soak the sample in 260°C±5°C					
heat resistance	ΔC	Within ±7.5%	Within ±20%	solder for 10±0.5				
	tanδ (%)	Satisfies the initial value	and humidity; me (Preheating Con	easure after 4				
	IR (*15)	10,000MΩ or 500MΩ•μF min., w	hichever is smaller	Order Te	mperature to 100°C	Time 2minutes		
	Withstand voltage (*15)	Resists without problem			0 to 200°C	2minutes		
Solderability	y	Ni/Br termination: 90% min.		Soaking Condition  Sn63 Solder 235±5°C 2±0.5sec.  Sn-3Ag-0.5Cu 245±5°C 3±0.5sec.  Do previous treatment (*8) (Cycle)				
Temperature cycle	Appearance	No significant change is detecte	d					
Сусіе	ΔC	Within ±7.5%	Within ±20%	Normal room temperature (3min.)→ Lowest operation temperature (30min.)→ Normal room temperature (3min.)→ Highest operation temperature (30min.)→				
	tanδ (%)	Satisfies the initial value						
	IR (*15)	10,000MΩ or 500MΩ•μF min., w	hichever is smaller	After five cycles, 48±4hours.	measure after	er		
	Withstand voltage (*15)	Resists without problem		40±4110d15.				
Load	Appearance	No significant change is detecte	d	Do previous trea After appling rate	` '			
humidity test (*11)	ΔC	Within ±12.5%	Within ±30%	40±2°C and hum	idty 90 to 95°			
	tanδ (%)	200% max. of initial value	150% max. of initial value	condition for 48±	4 hours then	measure		
	IR (*15)	500MΩ or 25MΩ•μF min., which	ever is smaller	and check the sp	ecilication lin	mies.		
High- temperature	Appearance	No significant change is detecte	d	Do previous trea After applying tw		rated		
with loading	ΔC	Within ±12.5%	Within ±30%	voltage at the hig	hest operatir	ng temperature		
	tanδ (%)	200% max. of initial value	150% max. of initial value	for 1000+48/–0h after storing 48±		e ine sample		
	IR (*15)	1,000MΩ or 50MΩ•μF min., whi						
	on the rated voltage is 250V		*10 For the CE series over 630\/ -					

<sup>1</sup> Use 1.5 times when the rated voltage is 250V or over.

Use 1.2 times when the rated voltage is 630V or over.

2 X7R 16V/25V type.

3 Apply to XSR16V/25V type, X7R 6.3V/10V type.

4 Apply to Y5V 16V type, CM32Y5V335 to 106 (25V Type).

5 Apply to Y5V 6.3V/10V type, Apply 16% to CM21Y5V106/CM316Y5V226.

6 Exclude CT series with thickness of less than 0.66mm and CA series.

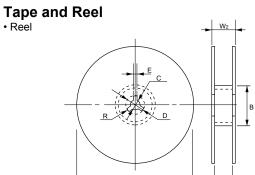
7 Use 1.5times when the rated voltage is 630V or over.

8 Keep specimen at 150°C+0/–10°C for one hour, leave specimen at room ambient for 48±4 hours.

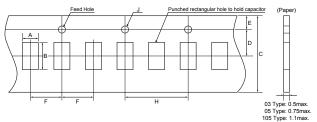
9 Apply the same test condition for one hour, then leave the specimen at room ambient for 48±4 hours.

<sup>\*10</sup> For the CF series over 630V, apply 500V for 1 minutes at room ambient.
\*11 Except CF series.
\*12 Apply to XSR 10V type.
\*13 Apply to ZSV series of CM105Y5V154 over, CM21Y5V105 over, 316Y5V155 over.
\*14 Measurement condition 1kHz, 1Vrms for Y5V, C < 47µF type.
\*15 The charge/discharge current of the capacitor must not exceed 50mA.
\*16 2N at 0201 Size
\*17 Apply to XSR 4V and 6.3V type.

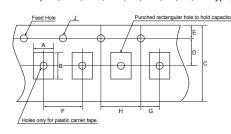


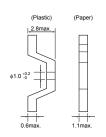


### F=2mm (03, 05, 105 Type)

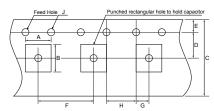


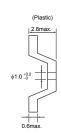
F=4mm (105, D11, D12, F12, 21, 316, 32, 42, 52 Type)

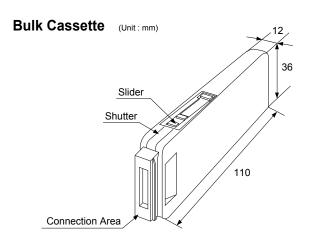




F=8mm (43, 53, 55 Type)







#### Reel (Unit : mm)

Code Reel	Α	В	С	D
7-inch Reel (CODE : T, H)	180 <sup>+0</sup> <sub>-0.2</sub>	φ60min.	nin. 13+0.5 21-	
13-inch Reel (CODE : L, N)	330±2.0	ф100±1.0	13±0.5	21±0.0
Code	Е	W <sub>1</sub>	W2	R
1/661				
7-inch Reel (CODE : T, H)	2.0±0.5	10.0±1.5	16.5max.	1.0

<sup>\*</sup>Carrier tape width 8mm. For size 42(1808) or over, Tape width 12mm and W1 : 14 $\pm$ 1.5, W2 : 18.4mm max.

### **Carrier Tape**

/1	Init	mm

Туре	Α	В	F
03 (0.6×0.3)	0.37±0.03	0.67±0.03	2.0±0.05
05 (1.0×0.5)	0.65±0.1	1.15±0.1	2.0±0.05
105 (1.6×0.8)	1.0±0.2	1.8±0.2	4.0±0.1
D11 (1.37×1.0)	1.15±0.1	1.55±0.1	4.0±0.1
D12 (1.25×2.0)	1.5±0.2	2.3±0.2	4.0±0.1
F12 (1.25×2.0)	1.5±0.2	2.3±0.2	4.0±0.1
21 (2.0×1.25)	1.5±0.2	2.3±0.2	4.0±0.1
316 (3.2×1.6)	2.0±0.2	3.6±0.2	4.0±0.1
32 (3.2×2.5)	2.9±0.2	3.6±0.2	4.0±0.1
42 (4.5×2.0)	2.4±0.2	4.9±0.2	4.0±0.1
43 (4.5×3.2)	3.6±0.2	4.9±0.2	8.0±0.1
52 (5.7×2.0)	2.4±0.2	6.0±0.2	4.0±0.1
53 (5.7×2.8)	3.2±0.2	6.0±0.2	8.0±0.1
55 (5.7×5.0)	5.3±0.2	6.0±0.2	8.0±0.1

(Unit : mm)

F	Carrier Tape	С	D	E	G	н	J
2.0 ±0.05	8mm Paper	0.0	2.5				
4.0	8mm	8.0 ±0.3	3.5 ±0.05	1.75	2.0	4.0	1.5
±0.1	Plastic			±0.1	±0.05		+0.1/-0
8.0 ±0.1	12mm Plastic	12.0 ±0.3	5.5 ±0.05				



### **Circuit Design**

- 1. Once application and assembly environments have been checked, the capacitor may be used in conformance with the rating and performance which are provided in both the catalog and the specifications. Use exceeding that which is specified may result in inferior performance or cause a short, open, smoking, or flaming to occur, etc.
- 2. Please consult the manufacturer in advance when the capacitor is used in devices such as: devices which deal with human life, i.e. medical devices; devices which are highly public orientated; and devices which demand a high standard of liability.
  - Accident or malfunction of devices such as medical devices, space equipment and devices having to do with atomic power could generate grave consequence with respect to human lives or, possibly, a portion of the public. Capacitors used in these devices may require high reliability design different from that of general purpose capacitors.
- 3. Please use the capacitors in conformance with the operating temperature provided in both the catalog and the specifications.
  - Be especially cautious not to exceed the maximum temperature. In the situation the maximum temperature set forth in both the catalog and specifications is exceeded, the capacitor's insulation resistance may deteriorate, power may suddenly surge and short-circuit may occur.
  - The capacitor has a loss, and may self-heat due to equivalent series resistance when alternating electric current is passed therethrough. As this effect becomes especially pronounced in high frequency circuits, please exercise caution.
  - When using the capacitor in a (self-heating) circuit, please make sure the surface of the capacitor remains under the maximum temperature for usage. Also, please make certain temperature rises remain below 20°C.
- 4. Please keep voltage under the rated voltage which is applied to the capacitor. Also, please make certain the peak voltage remains below the rated voltage when AC voltage is super-imposed to the DC voltage.
  - In the situation where AC or pulse voltage is employed, ensure average peak voltage does not exceed the rated voltage.
  - Exceeding the rated voltage provided in both catalog and specifications may lead to defective withstanding voltage or, in worst case situations, may cause the capacitor to smoke or flame.
- 5. When the capacitor is to be employed in a circuit in which there is continuous application of a high frequency voltage or a steep pulse voltage, even though it is within the rated voltage, please inquire to the manufacturer.
  - In the situation the capacitor is to be employed using a high frequency AC voltage or a extremely fast rising pulse voltage, even though it is within the rated voltage, it is possible capacitor reliability will deteriorate.
- 6. It is a common phenomenon of high-dielectric products to have a deteriorated amount of static electricity due to the application of DC voltage.

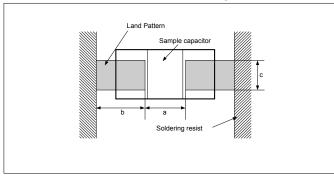
  Due caution is necessary as the degree of deterioration varies depending on the quality of capacitor materials, capacity, as well as the load voltage at the time of operation.
- 7. Do not use the capacitor in an environment where it might easily exceed the respective provisions concerning shock and vibration specified in the catalog and specifications.
  - In addition, it is a common piezo phenomenon of high dielectric products to have some Voltage due to vibration or to have noise due to Voltage change. Please contact sales in such case.
- 8. If the electrostatic capacity value of the delivered capacitor is within the specified tolerance, please consider this when designing the respective product in order that the assembled product function appropriately.
- 9. Please contact us upon using conductive adhesives.

### Storage

- 1. If the component is stored in minimal packaging (a heat-sealed or chuck-type plastic bag), the bag should be kept closed. Once the bag has been opened, reseal it or store it in a desiccator.
- 2. Keep storage place temperature +5 to +35 degree C, humidity 45 to 70% RH.
- 3. The storage atmosphere must be free of gas containing sulfur and chlorine. Also, avoid exposing the product to saline moisture. If the product is exposed to such atmospheres, the terminals will oxidize and solderability will be effected.
- 4. Precautions 1)-3) apply to chip capacitors packaged in carrier tapes and bulk cases.
- 5. The solderability is assured for 12 months from our shipping date (six months for silver palladium) if the above storage precautions are followed
- 6. Chip capacitors may crack if exposed to hydrogen (H2) gas while sealed or if coated with silicon, which generates hydrogen gas.



### **Dimensions for recommended typical land**



When mounting the capacitor to the substrate, it is important to consider carefully that the amount of solder (size of fillet) used has a direct effect upon the capacitor once it is mounted.

- a) The greater the amount of solder, the greater the stress to the elements. As this may cause the substrate to break or crack, it is important to establish the appropriate dimensions with regard to the amount of solder when designing the land of the substrate.
- b) In the situation where two or more devices are mounted onto a common land, separate the device into exclusive pads by using soldering resist

### **Standard**

(Unit : mm)

Size	9	L×W	а	b	С
03		0.6×0.3	0.20 to 0.30	0.25 to 0.35	0.30 to 0.40
05		1.0×0.5	0.30 to 0.50	0.35 to 0.45	0.40 to 0.60
105	5	1.6×0.8	0.70 to 1.00	0.80 to 1.00	0.60 to 0.80
21		2.0×1.25	1.00 to 1.30	1.00 to 1.20	0.80 to 1.10
316	;	3.2×1.6	2.10 to 2.50	1.10 to 1.30	1.00 to 1.30
32		3.2×2.5	2.10 to 2.50	1.10 to 1.30	1.90 to 2.30
42		4.5×2.0	2.50 to 3.20	1.80 to 2.30	1.50 to 1.80
43		4.5×3.2	2.50 to 3.20	1.80 to 2.30	2.60 to 3.00
52		5.7×2.0	4.20 to 4.70	2.00 to 2.50	1.50 to 1.80
53		5.7×2.8	4.20 to 4.70	2.00 to 2.50	2.20 to 2.60
55		5.7×5.0	4.20 to 4.70	2.00 to 2.50	4.20 to 4.70

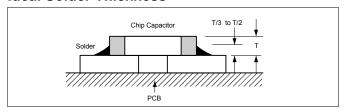
<sup>\*</sup> CA series : Please refer applicable page.

### **Automotive Series**

(Unit: mm)

Size	L×W	а	b	С
105	1.6×0.8	0.60 to 0.90	0.80 to 1.00	0.70 to 1.00
21	2.0×1.25	0.90 to 1.20	0.80 to 1.20	0.90 to 1.40
316	3.2×1.6	1.40 to 1.90	1.00 to 1.30	1.30 to 1.80

### **Ideal Solder Thickness**



### Typical mounting problems

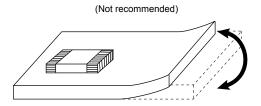
Typical mounting problems		
Item	Not recommended example	Recommended example/Separated by solder
Multiple parts mount		Solder resist
Mount with leaded parts	Leaded parts	Solder resist  Leaded parts
Wire soldering after mounting	Soldering iron Wire	Solder resist
Overview	Solder resist	Solder resist

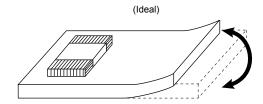


### **Mounting Design**

The chip could crack if the PCB warps during processing after the chip has been soldered.

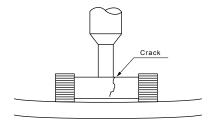
### Recommended chip position on PCB to minimize stress from PCB warpage

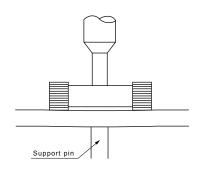




### **Actual Mounting**

- 1) If the position of the vacuum nozzle is too low, a large force may be applied to the chip capacitor during mounting, resulting in cracking.
- 2) During mounting, set the nozzle pressure to a static load of 100 to 300 gf.
- 3) To minimize the shock of the vaccum nozzle, provide a support pin on the back of the PCB to minimize PCB flexture.





- 4) Bottom position of pick up nozzle should be adjusted to the top surface of a substrate which camber is corrected.
- 5) To reduce the possibility of chipping and cracks, minimize vibration to chips stored in a bulk case.
- 6) The discharge pressure must be adjusted to the part size. Verify the pressure during setup to avoid fracturing or cracking the chips capacitors.

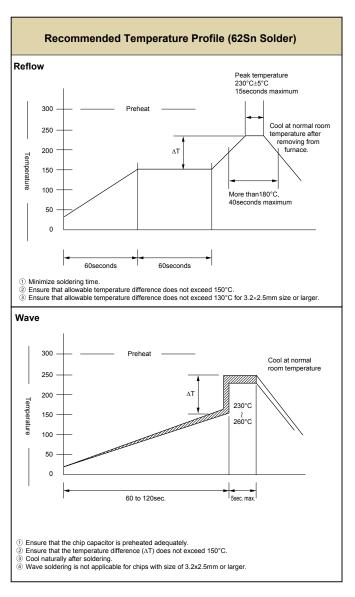
### **Resin Mold**

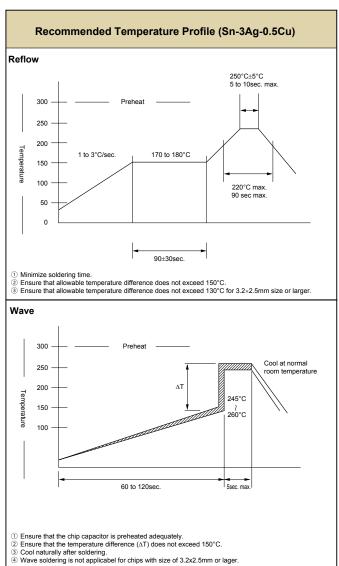
- 1) If a large amount of resin is used for molding the chip, cracks may occur due to contraction stress during curing. To avoid such cracks, use a low shrinkage resin.
- 2) The insulation resistance of the chip will degrade due to moisture absorption. Use a low moisture absorption resin.
- 3) Check carefully that the resin does not generate a decomposition gas or reaction gas during the curing process or during normal storage. Such gases may crack the chip capacitor or damage the device itself.



### **Soldering Method**

- 1) Ceramic is easily damaged by rapid heating or cooling. If some heat shock is unavoidable, preheat enough to limit the temperature difference (Delta T) to within 130 degree Celsius.
- 2) The product size 1.0×0.5mm to 3.2×1.6mm can be used in reflow and wave soldering, and the product size of over 3.2×2.5mm, 0.6×0.3mm, and capacitor arrays can be used in reflow.
  - Circuit shortage and smoking can be created by using capacitors which are used neglecting the above caution.
- 3) Please see our recommended soldering conditions.
  - Please contact us if you use lead free solder because the peak temperature of lead free is different from non-lead free.





### Sodering iron

1) Temperature of iron chip 380°C max.

2) Wattage 80W max.

3) Tip shape of soldering iron \$\phi 3.0mm max.

4) Soldering Time

3sec. max.

Cautions

a) Pre-heating is necessary Rapid heating must be avoided.

Delta T≤150°C.

- b) Avoid direct touching to capacitors.
- c) Avoid rapid cooling after soldering. Natural cooling is recommended.